

Electronic Patent Application Fee Transmittal

Application Number:	10774923			
Filing Date:	09-Feb-2004			
Title of Invention:	Direct build-up layer on an encapsulated die package having a moisture barrier structure			
First Named Inventor/Applicant Name:	Qing Ma			
Filer:	Joseph P. Mehrle/Anne Richards			
Attorney Docket Number:	884.803US2			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810